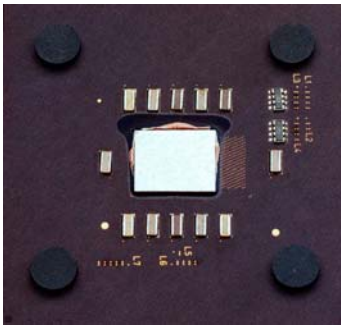


Application Study

ASSEMBLY OF FOAM PADS ONTO MICROPROCESSOR



TASK

Simultaneously peel and place four foam pads onto a microprocessor.

CHALLENGES

- In order to minimize raw material waste the pads were converted on the liner close together. This requires the pads to be repositioned prior to placement.
- Initial required cycle time is 5 seconds.
- Initial start up volumes required a temporary semi-automated solution with fast turnaround.

SOLUTION

- Model 3065
- Customized expanding chuck
- Customized nest
- Rewind reel
- Tape low sensor
- Bench top configuration for semi-automatic operation

FEATURES & BENEFITS

- Immediately after peeling four pads the customized expanding chuck orients the pads to their respective required placement positions.
- By assembling four pads simultaneously the cycle time objective of 5 seconds per assembly is achieved.
- The tape low sensor communicates to the host controller adhesive component roll status.
- During the start up phase of the project the bench top platform for intermittent stand-alone operation in conjunction with a customized nest were utilized. The machines were simply removed from the benchtop platforms and integrated with JEDEC tray feeders to boost thruput.
- The machine's compact footprint and simple communication interface made it easy to integrate into the automated production processes.

